

What is claimed is:

1. A method for inspecting a printing state comprising:
printing using a mask having i) a required portion, and ii) a test
portion, said test portion being provided in an area at a high risk of causing a defect
5 in a condition which has a high risk of causing a defect; and
judging the printing state of an entire printed material by inspecting
printing state of said test portion.
2. The method for inspecting a printing state as defined in Claim 1,
10 wherein a substrate to be printed is a circuit board.
3. The method for inspecting a printing state as defined in Claim 2,
wherein said method is for inspecting solder paste printed on said circuit board.
4. A method for inspecting a circuit board comprising:
printing a printing material on a circuit board using a mask having i) a
required portion, and ii) a test printing portion, said test printing portion having a
smaller pattern dimension than a smallest pattern dimension in said required portion;
inspecting a printing state of said test printing portion; and
20 judging the printing state of an entire circuit board based on a result of
said inspection.
5. The method for inspecting a circuit board as defined in Claims 4,
wherein said inspection uses one of an optical detection means and X ray.

6. The method for inspecting a circuit board as defined in Claim 4, wherein said printing material is solder paste.

7. The method for inspecting a circuit board as defined Claims 6
5 wherein said inspection uses one of an optical detection means and X ray.

8. The method for inspecting a circuit board as defined in Claim 6,
wherein said judgment of printing state is made based on one of "positional
deviation," "unclear," and "blur" of said printing material printed on said circuit
10 board.

9. The method for inspecting a circuit board as defined in Claim 7,
wherein said judgment of printing state is made based on one of "positional
deviation," "unclear," and "blur" of said printing material printed on said circuit
15 board.

10. The method for inspecting a circuit board as defined in Claim 4,
wherein said test printing portion is created at an area outside said required portion.

11. The method for inspecting a circuit board as defined in Claim 6,
20 wherein said test printing portion is created at an area outside said required portion.

12. The method for inspecting a circuit board as defined in Claim 4,
further comprising the step of notifying abnormality by judging means when said
25 printing state is judged to be "defective."

13. The method for inspecting a circuit board as defined in Claim 6, further comprising the step of notifying abnormality by judging means when said printing state is judged to be "defective."

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14. The method for inspecting a circuit board as defined in Claim 4, further comprising the step of changing a printing condition based on said judgement of a printing state.

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15. The method for inspecting a circuit board as defined in Claim 6, further comprising the step of changing a printing condition based on said judgement of a printing state.

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16. A substrate having a test printing portion other than a required printing portion on the substrate, said test printing portion having a pattern dimension smaller than a smallest pattern dimension formed on said required printing portion.

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17. The substrate as defined in Claim 16, wherein a material printed on said substrate is solder paste.

18. The substrate as defined in Claim 17, wherein said test printing portion is formed on an periphery outside an area where said required solder paste is printed.

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